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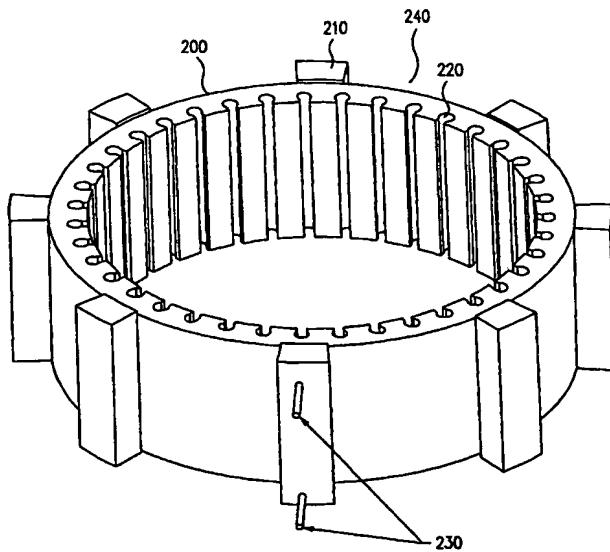
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(54) Title: VARIABLE HEATER ELEMENT FOR LOW TO HIGH TEMPERATURE RANGES



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(57) Abstract: A method and apparatus for insulating and controlling temperature in a semiconductor manufacturing environment. The invention comprises at least one modular heater element designed to be mounted about a semiconductor furnace process chamber in order to minimize thermal transfer between the furnace interior and exterior. A base ring or cylinder (200, 500, 700) also referred to as a heater ring is sized to be fitted around an inner skin of a semiconductor mini-batch furnace. The base ring (200, 500, 700) has multiple channels (220, 520) equidistantly spaced about its inner perimeter. Heating coils of a type well known in the art may nest in these channels in order to warm the furnace interior. The coils may be either removably or permanently affixed within the channels.

**Declaration under Rule 4.17:**

— as to applicant's entitlement to apply for and be granted a patent (Rule 4.17(ii)) for the following designations AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, UZ, VC, VN, YU, ZA, ZM, ZW, ARIPO patent (GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PT, RO, SE, SI, SK, TR), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG)

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